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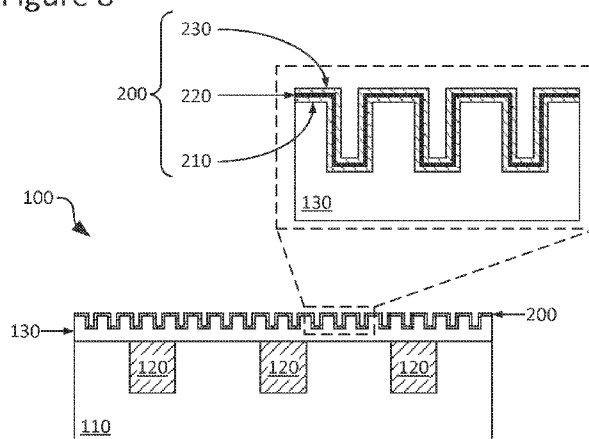
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(54) **Title:** METAL-INSULATOR-METAL CAPACITOR FORMATION TECHNIQUES

Figure 8



(57) **Abstract:** Techniques and structure are disclosed for providing a MIM capacitor having a generally corrugated profile. The corrugated topography is provisioned using sacrificial, self-organizing materials that effectively create a pattern in response to treatment (heat or other suitable stimulus), which is transferred to a dielectric material in which the MIM capacitor is formed. The self-organizing material may be, for example, a layer of directed self-assembly material that segregates into two alternating phases in response to heat or other stimulus, wherein one of the phases then can be selectively etched with respect to the other phase to provide the desired pattern. In another example case, the self-organizing material is a layer of material that coalesces into isolated islands when heated. As will be appreciated in light of this disclosure, the disclosed techniques can be used, for example, to increase capacitance per unit area, which can be scaled by etching deeper capacitor trenches/holes.